

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Noboru Morita, et al.



Serial No.: 10/766,921 Group Art Unit: Not Yet Assigned

Filing Date: January 30, 2004 Examiner: Unknown

For: METHOD OF FABRICATING SEMICONDUCTOR DEVICE USING PLASMA-ENHANCED CVD

Commissioner for Patents
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Under the provisions of 37 CFR §1.97 through §1.99 and pursuant to applicant's duty of disclosure under 37 CFR §1.56, applicant respectfully brings the following document listed on the attached form PTO-1449, to the attention of the Examiner in charge of the above-identified application. A copy of the listed document is provided herewith for the convenience of the Examiner.

This citation does not constitute an admission that the reference is relevant or material to the claims. It is only cited as constituting related art of which the applicant is aware.

It is respectfully requested that the listed reference be considered by the Examiner and formally made of record in this application.

Please charge any deficiencies in fees and credit any overpayment of fees to
Attorney's Deposit Account No. 50-0481.

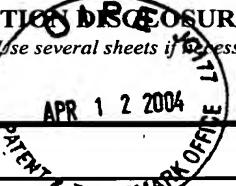
Respectfully submitted,

A handwritten signature in black ink, appearing to read "Sean M. McGinn".

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Date: 4/12/04

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INFORMATION DISCLOSURE CITATION <small>(Use several sheets if necessary)</small>				Docket Number (Optional) GNE518US		Application Number 10/766,921	
<i>APR 12 2004</i> 				Applicant(s) Noboru Morita, et al.			
				Filing Date January 30, 2004		Group Art Unit Unknown	
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
FOREIGN PATENT DOCUMENTS							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
OTHER DOCUMENTS <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>							
		Noguchi, et al., "TDDB IMPROVEMENT IN Cu METALLIZATION UNDER BIAS STRESS", 2000 IEEE, 38th Annual International Reliability Physics Symposium, pages 339-434					
EXAMINER				DATE CONSIDERED			